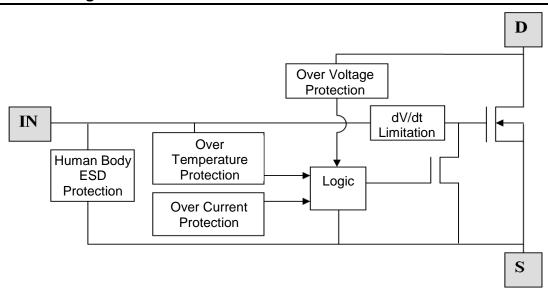
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Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise stated.)

Characteristic	Symbol	Value	Unit
Continuous Drain-Source Voltage	V _{DS}	60	V
Drain-Source Voltage for Short Circuit Protection	V _{DS(SC)}	36	V
Continuous Input Voltage	V _{IN}	-0.5 to +6	V
Continuous Input Current @-0.2V \leq V _{IN} \leq 6V Continuous Input Current @V _{IN} $<$ -0.2V or V _{IN} $>$ 6V	lin	No Limit I _{IN} ≤2	mA
Pulsed Drain Current @V _{IN} = 3.3V	I _{DM}	2	Α
Pulsed Drain Current @V _{IN} = 5V	I _{DM}	2.5	Α
Continuous Source Current (Body Diode) (Note 5)	Is	1	Α
Pulsed Source Current (Body Diode)	I _{SM}	5	Α
Unclamped Single Pulse Inductive Energy, T _J = +25°C, I _D = 0.5A, V _{DD} = 24V	E _{AS}	480	mJ
Electrostatic Discharge (Human Body Model)	V _{ESD}	4000	V
Charged Device Model	V _{CDM}	1000	V

Thermal Characteristics (@TA = +25°C, unless otherwise stated.)

Characteristic	Symbol	Value	Unit
Power Dissipation at T _A = +25°C (Note 5) Linear Derating Factor	P _D	1.0 8.0	W mW/°C
Power Dissipation at T _A = +25°C (Note 6) Linear Derating Factor	P _D	1.6 12.8	W mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	125	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	83	°C/W
Thermal Resistance, Junction to Case (Note 7)	R _{eJC}	39	°C/W
Operating Temperature Range	TJ	-40 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Note:

^{5.} For a device surface mounted on 15mm x 15mm single sided 1oz weight copper on 1.6mm FR-4 board, in still air conditions. Sink split drain 80% and source 20% to isolate connections.

^{6.} For a device surface mounted on 50mm x 50mm single sided 2oz weight copper on 1.6mm FR-4 board, in still air conditions. Sink split drain 80% and source 20% to isolate connections.

^{7.} Thermal resistance between junction and the mounting surfaces of drain and source pins.

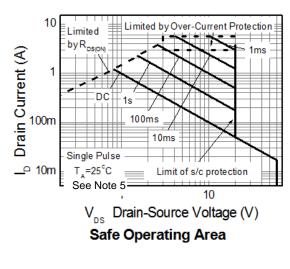


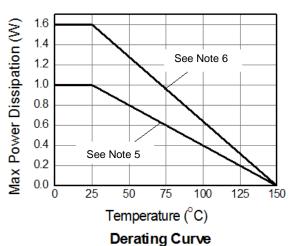
Recommended Operating Conditions

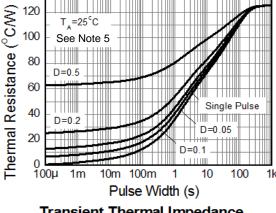
The ZXMS6004SG is optimized for use with μC operating from 3.3V and 5V supplies.

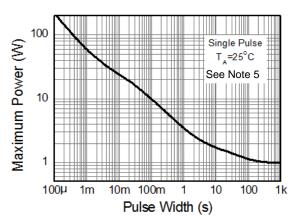
Characteristic	Symbol	Min	Max	Unit
Input Voltage Range	V _{IN}	0	5.5	V
Ambient Temperature Range	T _A	-40	+125	°C
High Level Input Voltage for MOSFET to be on	VIH	3	5.5	V
Low Level Input Voltage for MOSFET to be off	V _{IL}	0	0.7	V
Peripheral Supply Voltage (Voltage to Which Load is Referred)	V _P	0	36	V

Thermal Characteristics









Transient Thermal Impedance

Pulse Power Dissipation



Electrical Characteristics (@T_A = +25°C, unless otherwise stated.)

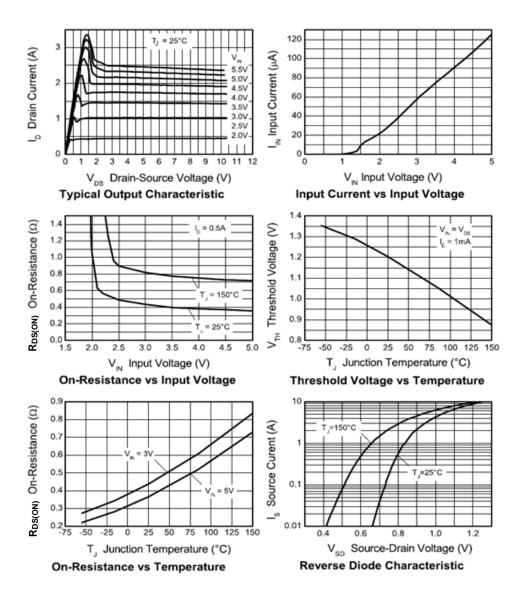
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Static Characteristics	•			•		·
Drain-Source Clamp Voltage	V _{DS(AZ)}	60	65	70	V	I _D = 10mA
Off State Drain Current		-	_	0.5	μΑ	V _{DS} = 12V, V _{IN} = 0V
On State Drain Current	I _{DSS}	_	_	1		V _{DS} = 36V, V _{IN} = 0V
Input Threshold Voltage	V _{IN(TH)}	0.7	1.2	1.5	V	$V_{DS} = V_{GS}$, $I_D = 1mA$
Input Current		-	60	100	μΑ	$V_{IN} = 3V$
Input Current	I _{IN}	-	120	200		V _{IN} = 5V
Input Current While Over Temperature Active	-	ı	-	400	μA	V _{IN} = 5V
Static Drain-Source On-State Resistance	D	ı	400	600	mΩ	$V_{IN} = 3V, I_D = 0.5A$
Static Dialii-Source Oil-State Resistance	R _{DS(ON)}	ı	350	500	11122	$V_{IN} = 5V, I_D = 0.5A$
Continuous Drain Current (Note 5)	- I _D	0.9	_	_		$V_{IN} = 3V; T_A = +25^{\circ}C$
		1	_	_	А	$V_{IN} = 5V; T_A = +25^{\circ}C$
Continuous Drain Current (Note 6)		1.2	_	_		$V_{IN} = 3V$; $T_A = +25$ °C
Continuous Diam Current (Note 0)		1.3	_	_		$V_{IN} = 5V$; $T_A = +25$ °C
Current Limit (Note 8)	I _{D(LIM)}	0.7	1.7	_	A	$V_{IN} = 3V$
Current Limit (Note 6)		1	2.2	_		$V_{IN} = 5V$
Dynamic Characteristics						
Turn On Delay Time	t _{D(ON)}	-	5	_		
Rise Time	t _R	ı	10	_		$V_{DD} = 12V, I_D = 0.5A, V_{GS} = 5V$
Turn Off Delay Time	t _{D(OFF)}	-	45	_	μs	
Fall Time	t _F	ı	15	_		
Over-Temperature Protection						
Thermal Overload Trip Temperature (Note 9)	T _{JT}	+150	+175	_	°C	-
Thermal Hysteresis (Note 9)	_	_	+10	_	°C	_

Notes:

The drain current is restricted only when the device is in saturation (see graph 'typical output characteristic'). This allows the device to be used in the fully on state without interference from the current limit. The device is fully protected at all drain currents, as the low power dissipation generated outside saturation makes current limit unnecessary.
 Over-temperature protection is designed to prevent device destruction under fault conditions. Fault conditions are considered as "outside" normal operating range, so this part is not designed to withstand over-temperature for extended periods.

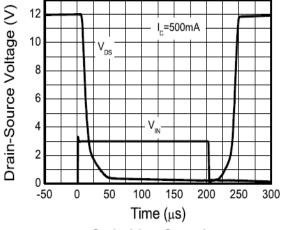


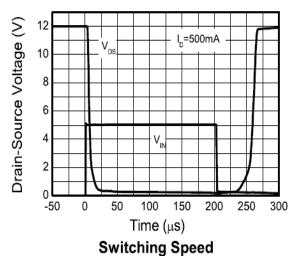
Typical Characteristics



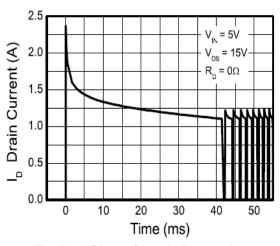


Typical Characteristics (Cont.)





Switching Speed

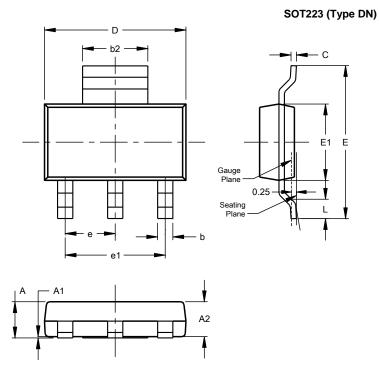


Typical Short Circuit Protection



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

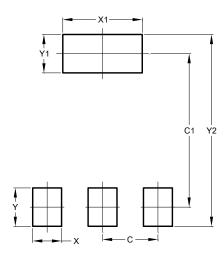


SOT223 (Type DN)					
Dim	Min	Max	Тур		
Α		1.70			
A1	0.01	0.15			
A2	1.50	1.68	1.60		
b	0.60	0.80	0.70		
b2	2.90	3.10			
С	0.20	0.32			
D	6.30	6.70			
Е	6.70	7.30			
E1	3.30	3.70			
е	-		2.30		
e1	1		4.60		
L	0.85				
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT223 (Type DN)



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00



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